## NPN - 2N6515, 2N6517; PNP - 2N6520

# **High Voltage Transistors NPN and PNP**

#### **Features**

- Voltage and Current are Negative for PNP Transistors
- These are Pb-Free Devices\*

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector – Emitter Voltage 2N6515 2N6517, 2N6520	V <sub>CEO</sub>	250 350	Vdc
Collector – Base Voltage 2N6515 2N6517, 2N6520	V <sub>CBO</sub>	250 350	Vdc
Emitter – Base Voltage 2N6515, 2N6517 2N6520	V <sub>EBO</sub>	6.0 5.0	Vdc
Base Current	I <sub>B</sub>	250	mAdc
Collector Current – Continuous	Ic	500	mAdc
Total Device Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	625 5.0	mW mW/°C
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	1.5 12	W mW/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

#### THERMAL CHARACTERISTICS

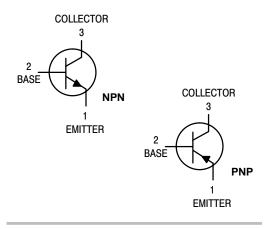
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	83.3	°C/W

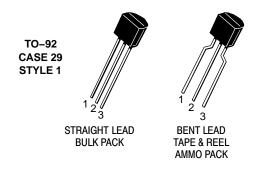
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



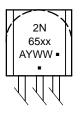
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#### **MARKING DIAGRAM**



xx = 15, 17, or 20

A = Assembly Location

Y = Year

WW = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### NPN - 2N6515, 2N6517; PNP - 2N6520

#### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS	l		I.	1	1
Collector-Emitter Breakdown Voltage (Note 1) $(I_C = 1.0 \text{ mAdc}, I_B = 0)$	2N6515 2N6517, 2N6520	V <sub>(BR)CEO</sub>	250 350	_ _	Vdc
Collector–Base Breakdown Voltage ( $I_C$ = 100 $\mu$ Adc, $I_E$ = 0 )	2N6515 2N6517, 2N6520	V <sub>(BR)CBO</sub>	250 350	_ _	Vdc
Emitter–Base Breakdown Voltage ( $I_E = 10 \mu Adc, I_C = 0$ )	2N6515, 2N6517 2N6520	$V_{(BR)EBO}$	6.0 5.0	_ _	Vdc
Collector Cutoff Current $(V_{CB} = 150 \text{ Vdc}, I_E = 0)$ $(V_{CB} = 250 \text{ Vdc}, I_E = 0)$	2N6515 2N6517, 2N6520	I <sub>CBO</sub>	- -	50 50	nAdc
Emitter Cutoff Current ( $V_{EB} = 5.0 \text{ Vdc}$ , $I_{C} = 0$ ) ( $V_{EB} = 4.0 \text{ Vdc}$ , $I_{C} = 0$ )	2N6515, 2N6517 2N6520	I <sub>EBO</sub>		50 50	nAdc
ON CHARACTERISTICS (Note 1)					
DC Current Gain (I <sub>C</sub> = 1.0 mAdc, V <sub>CE</sub> = 10 Vdc)	2N6515 2N6517, 2N6520	h <sub>FE</sub>	35 20	_ _	-
$(I_C = 10 \text{ mAdc}, V_{CE} = 10 \text{ Vdc})$	2N6515 2N6517, 2N6520		50 30	_ _	
$(I_C = 30 \text{ mAdc}, V_{CE} = 10 \text{ Vdc})$	2N6515 2N6517, 2N6520		50 30	300 200	
$(I_C = 50 \text{ mAdc}, V_{CE} = 10 \text{ Vdc})$	2N6515 2N6517, 2N6520		45 20	220 200	
$(I_C = 100 \text{ mAdc}, V_{CE} = 10 \text{ Vdc})$	2N6515 2N6517, 2N6520		25 15	-	
Collector–Emitter Saturation Voltage ( $I_C$ = 10 mAdc, $I_B$ = 1.0 mAdc) ( $I_C$ = 20 mAdc, $I_B$ = 2.0 mAdc) ( $I_C$ = 30 mAdc, $I_B$ = 3.0 mAdc) ( $I_C$ = 50 mAdc, $I_B$ = 5.0 mAdc)		V <sub>CE(sat)</sub>	- - - -	0.30 0.35 0.50 1.0	Vdc
Base-Emitter Saturation Voltage ( $I_C = 10 \text{ mAdc}$ , $I_B = 1.0 \text{ mAdc}$ ) ( $I_C = 20 \text{ mAdc}$ , $I_B = 2.0 \text{ mAdc}$ ) ( $I_C = 30 \text{ mAdc}$ , $I_B = 3.0 \text{ mAdc}$ )		V <sub>BE(sat)</sub>	- - -	0.75 0.85 0.90	Vdc
Base–Emitter On Voltage (I <sub>C</sub> = 100 mAdc, V <sub>CE</sub> = 10 Vdc)		$V_{\text{BE(on)}}$	_	2.0	Vdc
SMALL-SIGNAL CHARACTERISTICS				•	
Current-Gain - Bandwidth Product (Note 1) (I <sub>C</sub> = 10 mAdc, V <sub>CE</sub> = 20 Vdc, f = 20 MHz)		f <sub>T</sub>	40	200	MHz
Collector–Base Capacitance (V <sub>CB</sub> = 20 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)		C <sub>cb</sub>	_	6.0	pF
Emitter–Base Capacitance $(V_{EB} = 0.5 \text{ Vdc}, I_C = 0, f = 1.0 \text{ MHz})$	2N6515, 2N6517 2N6520	C <sub>eb</sub>	- -	80 100	pF
SWITCHING CHARACTERISTICS					
Turn–On Time $(V_{CC} = 100 \text{ Vdc}, V_{BE(off)} = 2.0 \text{ Vdc}, I_C = 50 \text{ mAdc}, I_{B1} = 1.0 \text{ MHz}$	10 mAdc)	t <sub>on</sub>	_	200	μs
Turn–Off Time ( $V_{CC} = 100 \text{ Vdc}$ , $I_C = 50 \text{ mAdc}$ , $I_{B1} = I_{B2} = 10 \text{ mAdc}$ )		t <sub>off</sub>	-	3.5	μS

<sup>1.</sup> Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

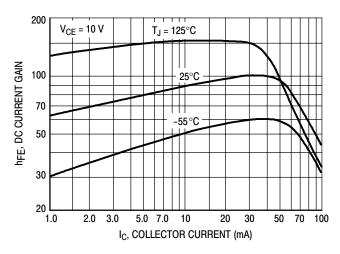


Figure 1. DC Current Gain NPN 2N6515

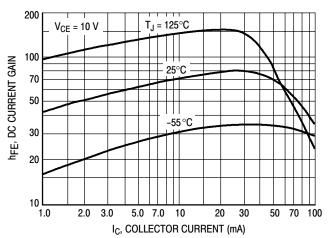


Figure 2. DC Current Gain NPN 2N6517

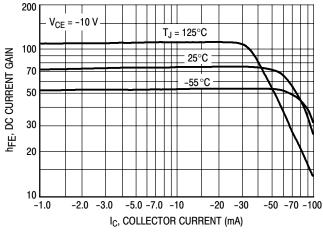


Figure 3. DC Current Gain PNP 2N6520

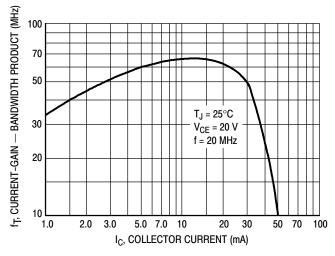


Figure 4. Current-Gain – Bandwidth Product NPN 2N6515, 2N6517

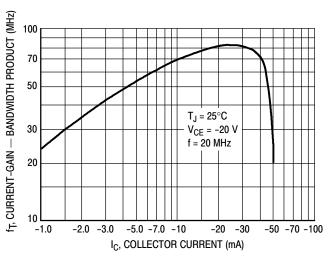


Figure 5. Current–Gain – Bandwidth Product PNP 2N6520

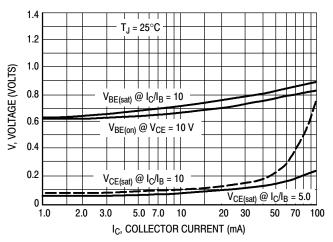


Figure 6. "On" Voltages NPN 2N6515, 2N6517

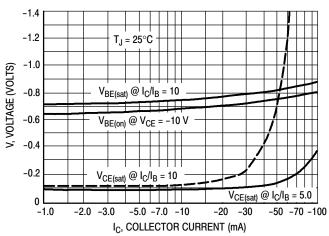


Figure 7. "On" Voltages PNP 2N6520

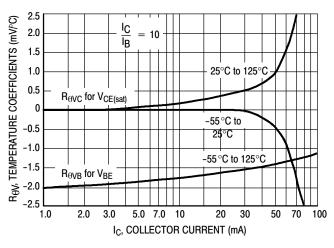


Figure 8. Temperature Coefficients NPN 2N6515, 2N6517

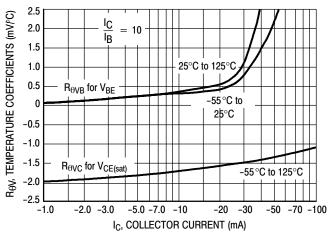


Figure 9. Temperature Coefficients PNP 2N6520

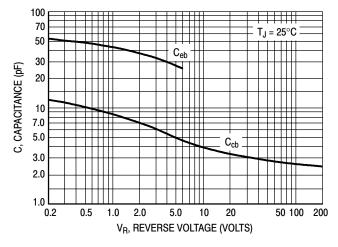


Figure 10. Capacitance NPN 2N6515, 2N6517

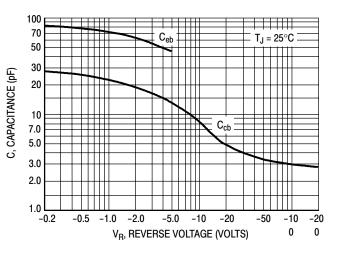
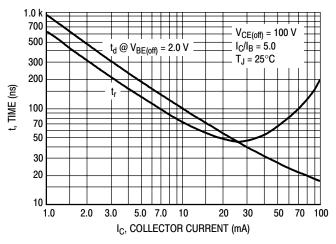


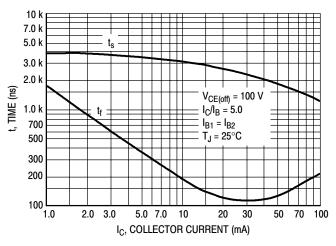
Figure 11. Capacitance PNP 2N6520



1.0 k 700  $V_{CE(off)} = -100 \text{ V}$  $t_d @ V_{BE(off)} = 2.0 V$ 500  $I_{C}/I_{B} = 5.0$  $T_J=25^{\circ}C$ 300 200 t, TIME ( 100 70 50 30 20 10 -1.0 -5.0 -7.0 -10 -50 -70 -100 I<sub>C</sub>, COLLECTOR CURRENT (mA)

Figure 12. Turn-On Time NPN 2N6515, 2N6517

Figure 13. Turn-On Time PNP 2N6520



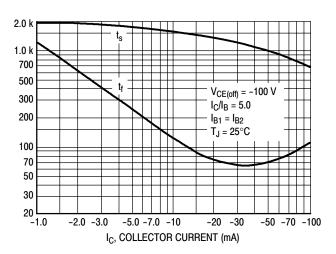


Figure 14. Turn-Off Time NPN 2N6515, 2N6517

Figure 15. Turn-Off Time PNP 2N6520

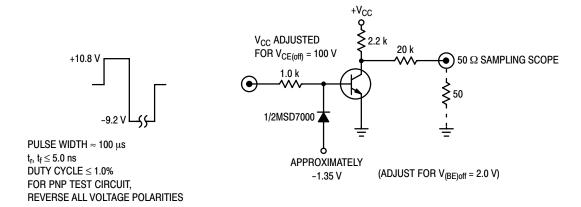


Figure 16. Switching Time Test Circuit

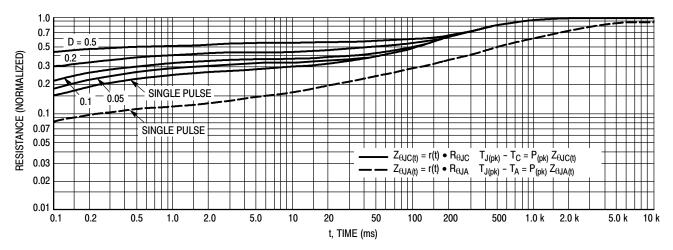


Figure 17. Thermal Response

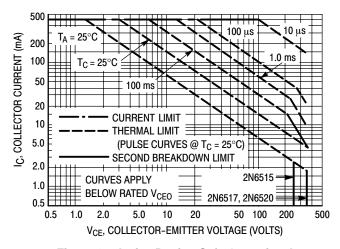
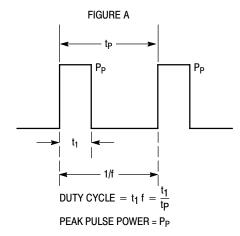


Figure 18. Active Region Safe Operating Area

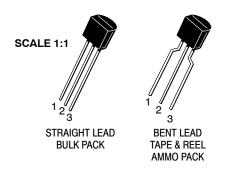


Design Note: Use of Transient Thermal Resistance Data

#### **ORDERING INFORMATION**

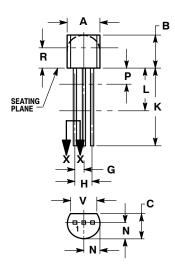
Device	Package	Shipping <sup>†</sup>
2N6515RLRMG	TO-92 (Pb-Free)	2000 Ammo Pack
2N6517G	TO-92 (Pb-Free)	5000 Unit / Bulk
2N6517RLRPG	TO-92 (Pb-Free)	2000 Ammo Pack
2N6520RLRAG	TO-92 (Pb-Free)	2000 Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



**TO-92 (TO-226)** CASE 29-11 **ISSUE AM** 

**DATE 09 MAR 2007** 

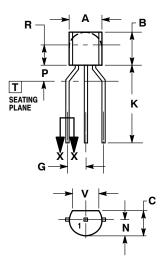


STRAIGHT LEAD **BULK PACK** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
  4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500		12.70	
L	0.250		6.35	
N	0.080	0.105	2.04	2.66
P		0.100		2.54
R	0.115		2.93	
V	0.135		3.43	



**BENT LEAD** TAPE & REEL AMMO PACK



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
  4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	MILLIMETERS			
DIM	MIN	MAX		
Α	4.45	5.20		
В	4.32	5.33		
С	3.18	4.19		
D	0.40	0.54		
G	2.40	2.80		
J	0.39	0.50		
K	12.70			
N	2.04	2.66		
P	1.50	4.00		
R	2.93			
٧	3.43			

#### **STYLES ON PAGE 2**

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# **TO-92 (TO-226)** CASE 29-11

# ISSUE AM

#### DATE 09 MAR 2007

STYLE 1: PIN 1. 2. 3.	EMITTER BASE COLLECTOR	STYLE 2: PIN 1. 2. 3.	BASE EMITTER COLLECTOR	STYLE 3: PIN 1. 2. 3.	ANODE ANODE CATHODE	STYLE 4: PIN 1. 2. 3.	CATHODE CATHODE ANODE	STYLE 5: PIN 1. 2. 3.	DRAIN SOURCE GATE
STYLE 6: PIN 1. 2. 3.	GATE SOURCE & SUBSTRATE DRAIN	STYLE 7: PIN 1. 2. 3.	SOURCE DRAIN GATE	STYLE 8: PIN 1. 2. 3.	DRAIN GATE SOURCE & SUBSTRATE	STYLE 9: PIN 1. 2. 3.	BASE 1 EMITTER BASE 2	STYLE 10: PIN 1. 2. 3.	CATHODE GATE ANODE
2. 3.	CATHODE & ANODE CATHODE	2. 3.	GATE MAIN TERMINAL 2	2. 3.		2. 3.	COLLECTOR BASE	2. 3.	CATHODE ANODE 2
STYLE 16: PIN 1. 2. 3.	ANODE GATE CATHODE	STYLE 17: PIN 1. 2. 3.	COLLECTOR BASE EMITTER	STYLE 18: PIN 1. 2. 3.	ANODE CATHODE NOT CONNECTED	STYLE 19: PIN 1. 2. 3.	GATE ANODE CATHODE	STYLE 20: PIN 1. 2. 3.	NOT CONNECTED CATHODE ANODE
2.	COLLECTOR EMITTER BASE	STYLE 22: PIN 1. 2. 3.	SOURCE GATE DRAIN	STYLE 23: PIN 1. 2. 3.	GATE SOURCE DRAIN	PIN 1	EMITTER COLLECTOR/ANODE CATHODE	PIN 1	MT 1
	V <sub>CC</sub> GROUND 2 OUTPUT								
STYLE 31: PIN 1. 2. 3.	GATE DRAIN SOURCE	STYLE 32: PIN 1. 2. 3.	BASE COLLECTOR EMITTER	STYLE 33: PIN 1. 2. 3.	RETURN INPUT OUTPUT	STYLE 34: PIN 1. 2. 3.	INPUT GROUND LOGIC	STYLE 35: PIN 1. 2. 3.	GATE COLLECTOR EMITTER

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98ASB42022	В

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